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Renesas Technology Corp. Customer Support Dept. April 1, 2003



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HSS104

Silicon Epitaxial Planar Diode for High Speed Switching



ADE-208-178B (Z)

Rev.2 Oct. 2000

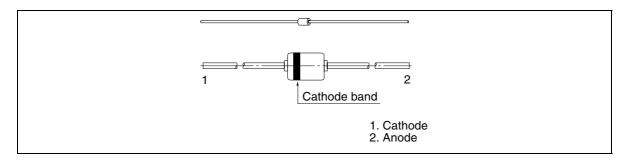
Features

- Short reverse recovery time and forward recovery time.
- Suitable for 5 mm pitch high speed automatically insertion.
- Small glass package (MHD) enables easy mounting and high reliability.

Ordering Information

Type No.	Cathode band	Package Code
HSS104	Blue	MHD

Pin Arrangement



HSS104

Absolute Maximum Ratings

 $(Ta = 25^{\circ}C)$

Item	Symbol	Value	Unit	
Peak reverse voltage	V _{RM}	40	V	
Reverse voltage	V _R	35	V	
Average rectified current	I _o	110	mA	
Peak forward current	I _{FM}	300	mA	
Non-Repetitive peak forward surge current	FSM *	0.4	Α	
Power dissipation	Pd	300	mW	
Junction temperature	Tj	175	°C	
Storage temperature	Tstg	-65 to +175	°C	

Note: Within 1s forward surge current.

Electrical Characteristics

 $(Ta = 25^{\circ}C)$

Item	Symbol	Min	Тур	Max	Unit	Test Condition
Forward voltage	V _F	_	_	1.2	V	I _F = 100 mA
Reverse current	I _R	_	_	0.5	μΑ	V _R = 35 V
Capacitance	С	_	_	3.0	pF	V _R = 0.5 V, f = 1 MHz
Reverse recovery time	t _{rr}	_		3.0	ns	$I_F = 10 \text{ mA}, V_R = 6 \text{ V}, R_L = 50 \Omega$

Main Characteristic

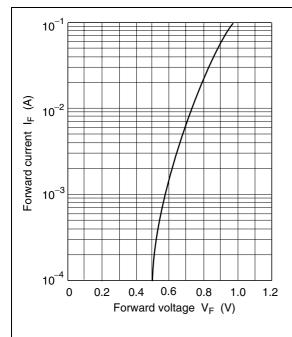
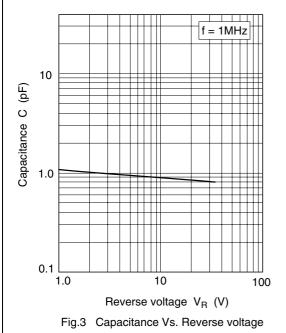


Fig.1 Forward current Vs. Forward voltage



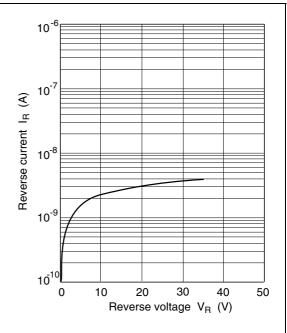
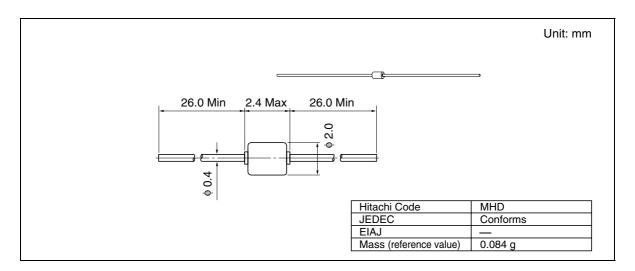


Fig.2 Reverse current Vs. Reverse voltage

HSS104

Package Dimensions



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